

• General Description

The AGM318D combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

This device is ideal for load switch and battery protection applications.

• Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

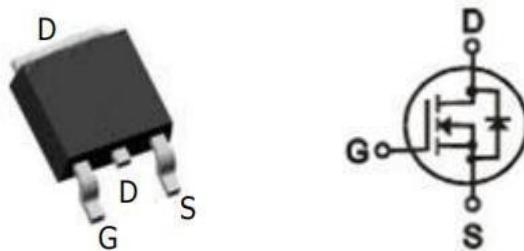
• Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

BVDSS	RDS(on)	ID
30V	18mΩ	20A

TO-252 Pin Configuration



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AAGM318D	AGM318D	TO-252	-----	----	2500

Table 1. Absolute Maximum Ratings (TA=25°C)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	30	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	± 20	V
I_D	Drain Current-Continuous($T_c=25^\circ C$) ^(Note 1)	20	A
	Drain Current-Continuous($T_c=100^\circ C$)	12	A
IDM (pulse)	Drain Current-Continuous@ Current-Pulsed ^(Note 2)	32	A
P_D	Total Power Dissipation($T_c=25^\circ C$)	3.8	W
	Total Power Dissipation($TA=100^\circ C$)	1.4	W
EAS	Avalanche energy ^(Note 3)	99	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient (Steady State) ¹	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	34	°C/W

Table 3. N- Channel Electrical Characteristics (TA=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	30	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=30V, VGS=0V	--	--	1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V, VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=250μA	1.0	1.6	3.0	V
gFS	Forward Transconductance	VDS=5V, ID=5A	--	5.2	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=11A	--	18	27	mΩ
		VGS=4.5V, ID=8A	--	28	37	mΩ
Dynamic Characteristics						
Ciss	Input Capacitance	VDS=10V, VGS=0V, F=1MHZ	--	333	--	pF
Coss	Output Capacitance		--	94	--	pF
Crss	Reverse Transfer Capacitance		--	75	--	pF
Rg	Gate resistance	VGS=0V, VDS=0V, f=1.0MHz	--	--	--	Ω
Switching Times						
td(on)	Turn-on Delay Time	VGS=10V, VDS=15V, RL=15Ω, RGEN=6Ω, ID=5A	--	7.4	--	nS
tr	Turn-on Rise Time		--	2.4	--	nS
td(off)	Turn-Off Delay Time		--	18.4	--	nS
tf	Turn-Off Fall Time		--	4.0	--	nS
Qg	Total Gate Charge	VGS=10V, VDS=10V, ID=5A	--	8.6	--	nC
Qgs	Gate-Source Charge		--	2.1	--	nC
Qgd	Gate-Drain Charge		--	1.1	--	nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)		--	--	20	A
VSD	Forward on Voltage	VGS=0V, IS=5A	--	--	1.2	V
trr	Reverse Recovery Time	IF=5A, dI/dt=100A/μs, TJ=25°C	--	--	--	ns
Qrr	Reverse Recovery Charge		--	--	--	nc

Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25°C

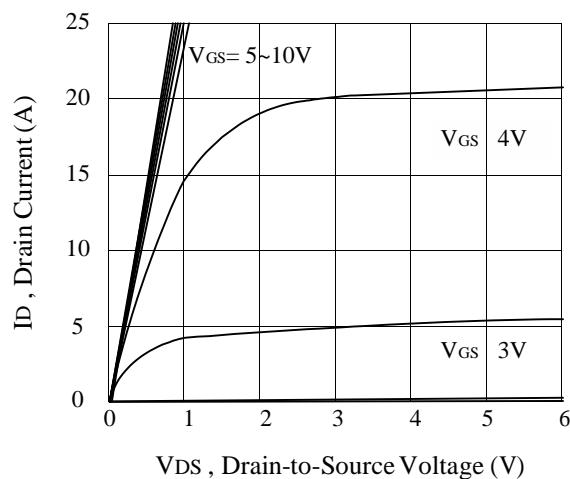


Figure 1. Output Characteristics

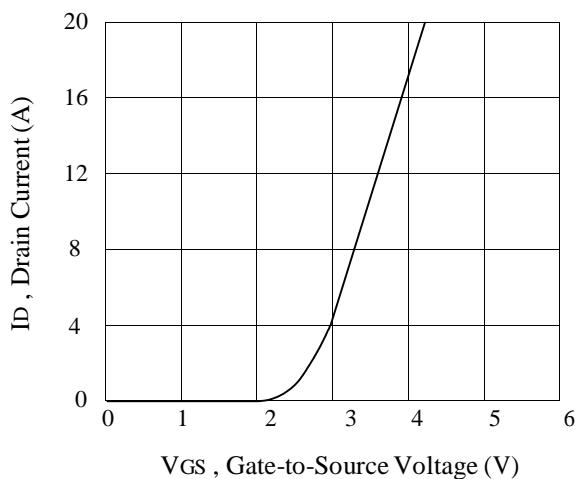


Figure 2. Transfer Characteristics

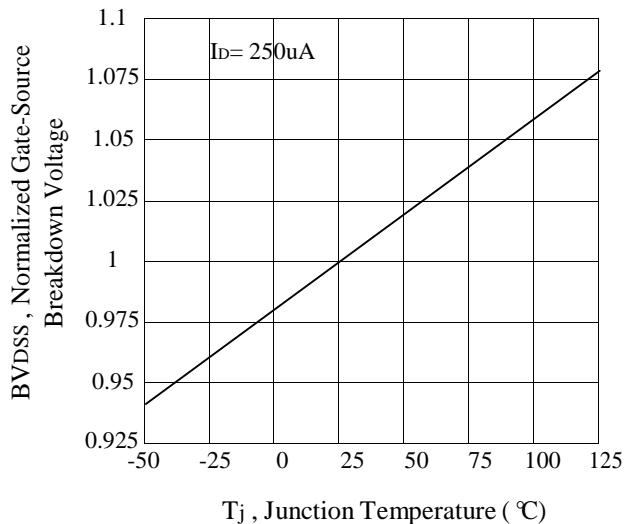


Figure 3. Breakdown Voltage Variation with Temperature

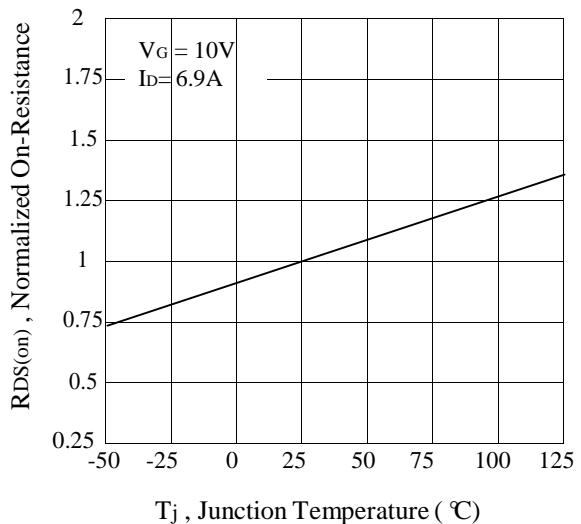


Figure 4. On-Resistance Variation with Temperature

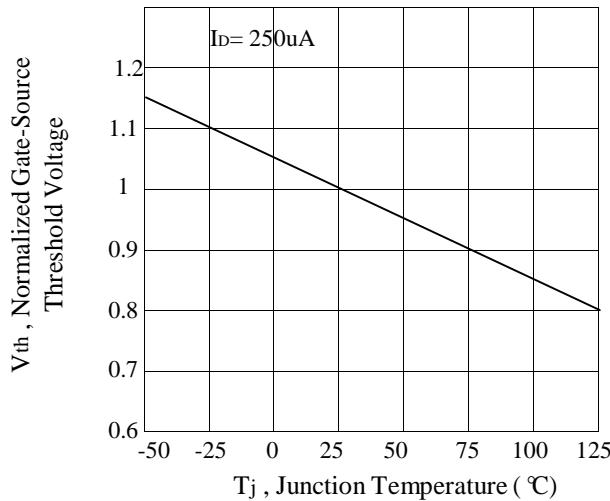


Figure 5. Gate Threshold Variation with Temperature

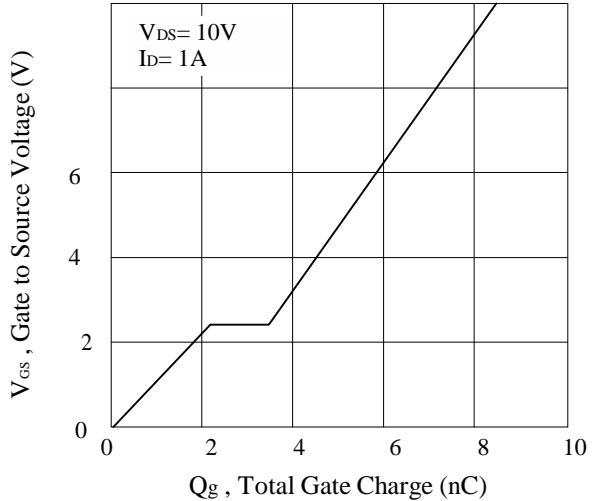


Figure 6. Gate Charge

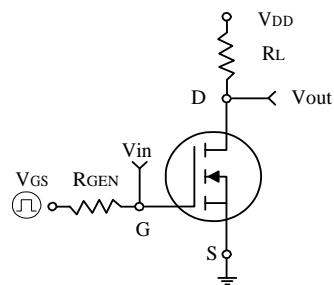
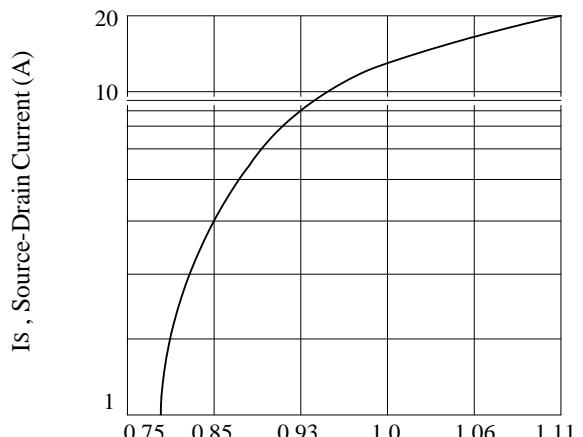
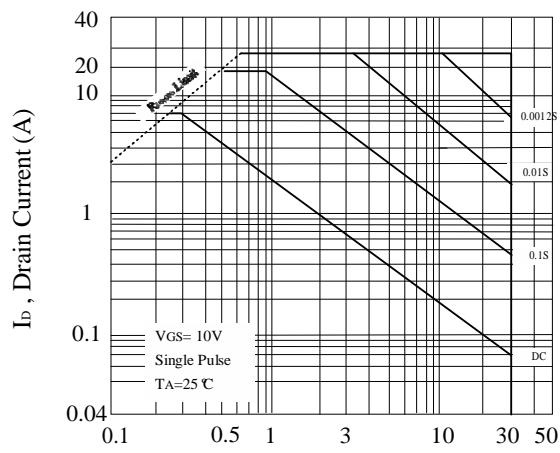
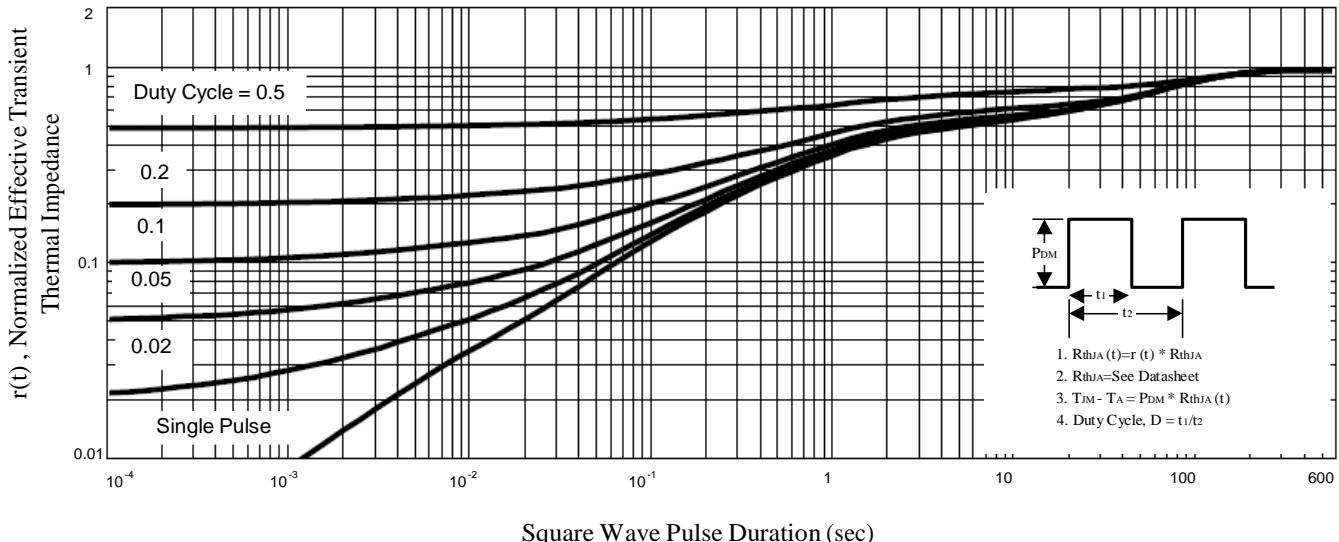
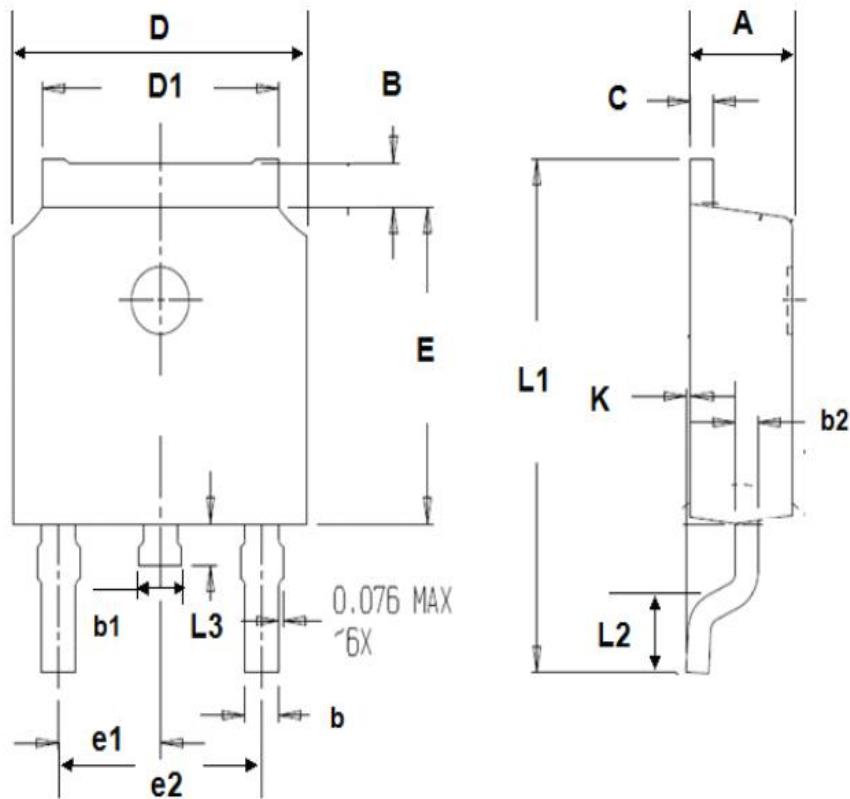


Figure 9. Switching Test Circuit and Switching Waveforms



•Dimensions

SYMBOL	min	max	SYMBOL	min	max
A	2.10	2.50	B	0.85	1.25
b	0.50	0.80	b1	0.50	0.90
b2	0.45	0.70	C	0.45	0.70
D	6.30	6.75	D1	5.10	5.50
E	5.30	6.30	e1	2.25	2.35
L1	9.20	10.60	e2	4.45	4.75
L2	0.90	1.75	L3	0.60	1.10
K	0.00	0.23			



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